

## HVL397C

### Variable Capacitance Diode for VCO

REJ03G0023-0200  
Rev.2.00  
Mar 16, 2006

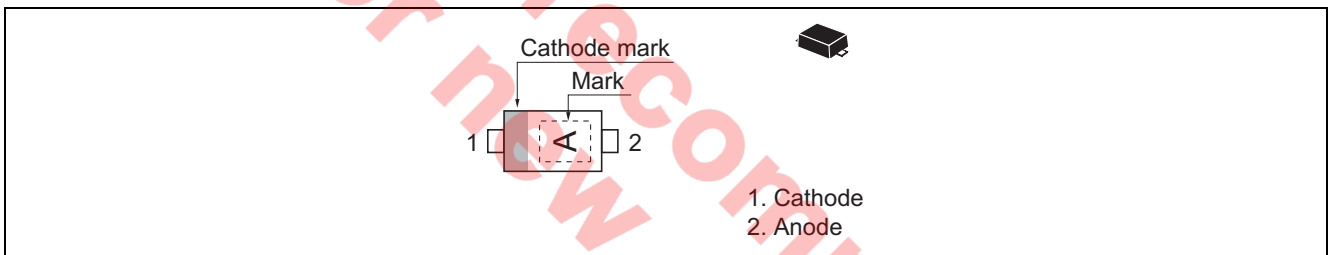
#### Features

- High capacitance ratio. (n = 2.9 min)
- Good C-V linearity
- Extremely small Flat Lead Package (EFP) is suitable for surface mount design.

#### Ordering Information

Type No.	Laser Mark	Package Name	Package Code
HVL397C	A	EFP	PXSF0002ZA-A

#### Pin Arrangement



## Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	$V_R$	15	V
Junction temperature	$T_j$	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

## Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	$I_{R1}$	—	—	10	nA	$V_R = 10\text{ V}$
	$I_{R2}$	—	—	50		$V_R = 10\text{ V}, T_a = 60^\circ\text{C}$
Capacitance	$C_1$	27.0	—	28.5	pF	$V_R = 1\text{ V}, f = 1\text{ MHz}$
	$C_2$	18.0	—	20.0		$V_R = 2\text{ V}, f = 1\text{ MHz}$
	$C_4$	6.80	—	8.50		$V_R = 4\text{ V}, f = 1\text{ MHz}$
Capacitance ratio	$n_1$	1.3	—	—	—	$C_1 / C_2$
	$n_2$	2.9	—	—	—	$C_1 / C_4$
Series resistance	$r_s$	—	—	1.2	$\Omega$	$V_R = 1\text{ V}, f = 470\text{ MHz}$

Note: For EFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic

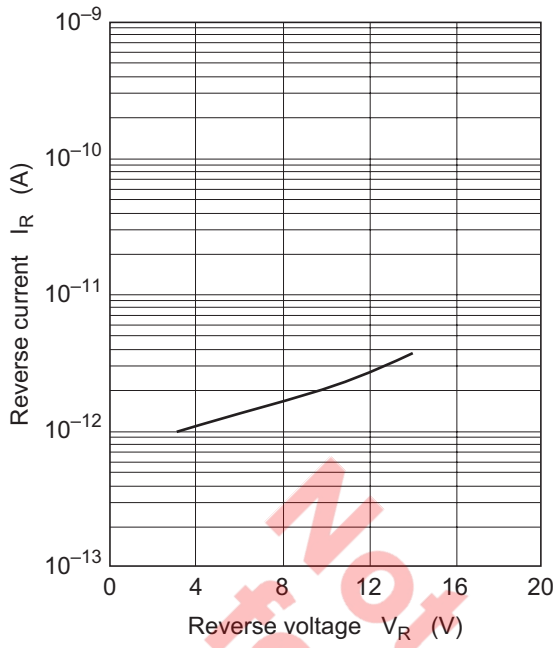


Fig.1 Reverse current vs. Reverse voltage

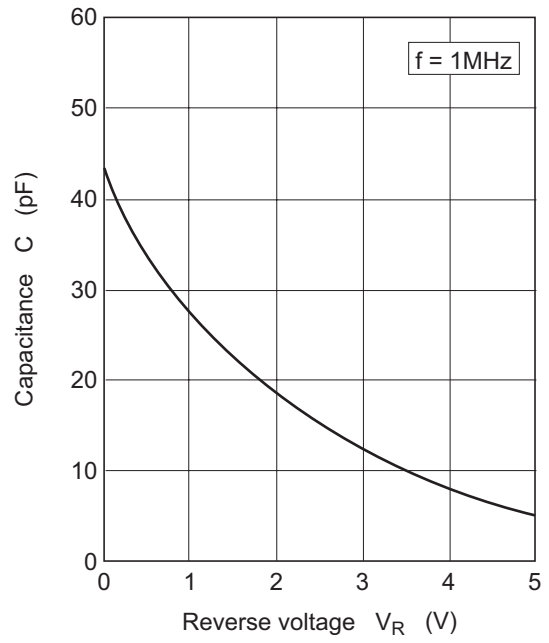


Fig.2 Capacitance vs. Reverse voltage

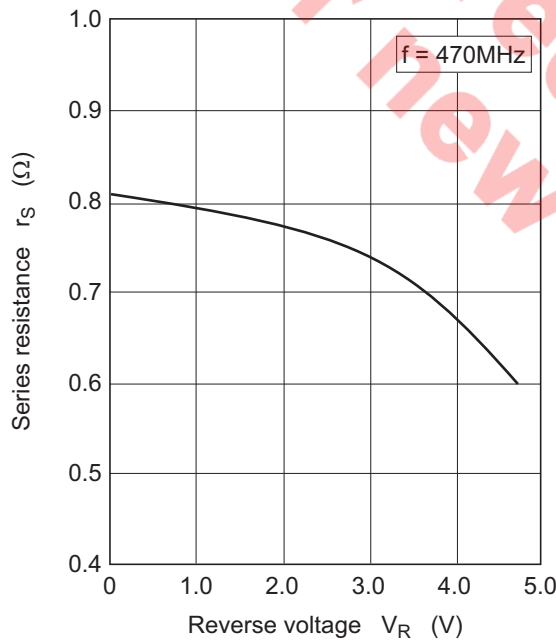
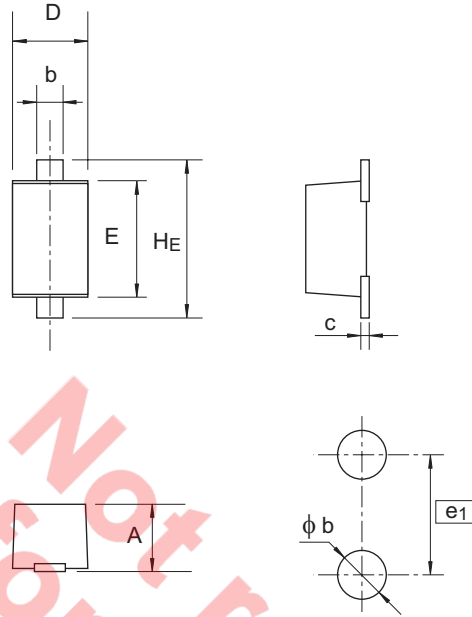


Fig.3 Series resistance vs. Reverse voltage

Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
EFP	—	PXSF0002ZA-A	EFP / EFPV	0.0007g



Pattern of terminal position areas

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	0.44	0.47	0.50
b	0.25	0.30	0.35
c	0.08	0.13	0.18
D	0.55	0.60	0.65
E	0.75	0.80	0.85
HE	0.95	1.00	1.05
phi b	—	0.40	—
e1	—	1.00	—

Not recommended for new design

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450 Holger Way, San Jose, CA 95134-1368, U.S.A  
Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

### **Renesas Technology Europe Limited**

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.  
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

### **Renesas Technology (Shanghai) Co., Ltd.**

Unit 204, 205, AZIACenter, No.1233 Lujiazui Ring Rd, Pudong District, Shanghai, China 200120  
Tel: <86> (21) 5877-1818, Fax: <86> (21) 6887-7898

### **Renesas Technology Hong Kong Ltd.**

7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong  
Tel: <852> 2265-6688, Fax: <852> 2730-6071

### **Renesas Technology Taiwan Co., Ltd.**

10th Floor, No.99, Fushing North Road, Taipei, Taiwan  
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

### **Renesas Technology Singapore Pte. Ltd.**

1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632  
Tel: <65> 6213-0200, Fax: <65> 6278-8001

### **Renesas Technology Korea Co., Ltd.**

Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea  
Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

### **Renesas Technology Malaysia Sdn. Bhd**

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia  
Tel: <603> 7955-9390, Fax: <603> 7955-9510